



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON ,GLASS FIBER FILLED,UL94V-0, COLOR: BLACK,
 (b) POLYESTER , GLASS FIBER FILLED,UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

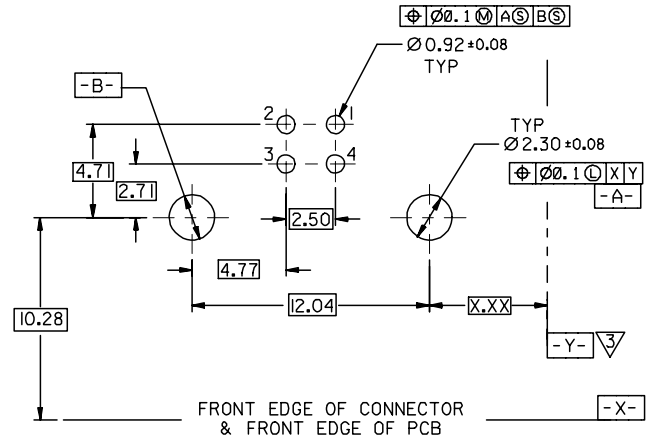
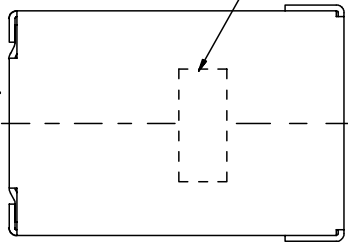
METAL SHELL :
 PURE TIN(Sn) , THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni) , THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

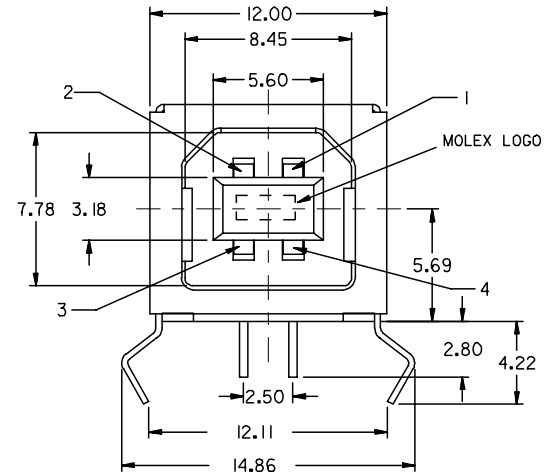
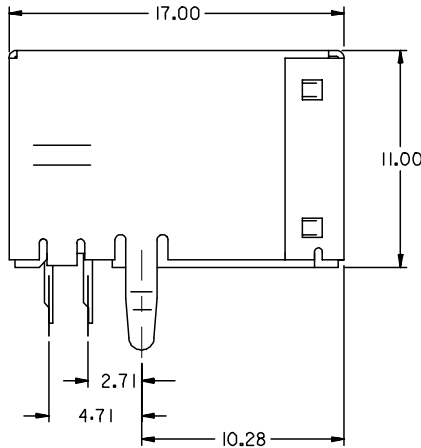
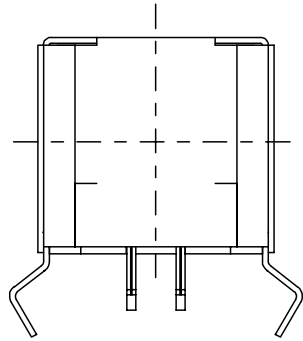
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

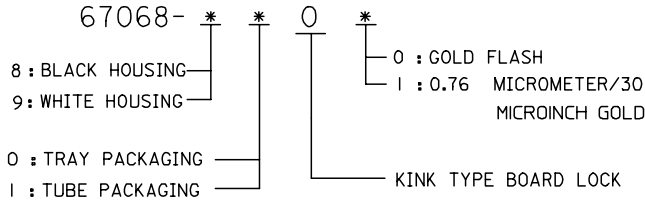
MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR & FRONT EDGE OF PCB
 RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:



NEW RELEASE	DESCRIPTION
EC NO: SH2005-0142	DRWN: DAVID HU 2004/11/5
CHKD: HARVEY 2004/11/25	APPR: TYAP 2004/11/25
REV	DESCRIPTION
A	

QUALITY SYMBOLS
▽=0
▽C=0

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.25	± ---
1 PLACE ± 0.25	± ---
ANGULAR ± 3 °	

DIMENSION STYLE		SCALE		DESIGN UNITS	
MM ONLY		4:1		METRIC	
DRAWN BY	DATE	TITLE	THIRD ANGLE PROJECTION		
DAVID HU	2004/11/05	USB B TYPE CONNECTOR			
CHECKED BY	DATE	KINK TYPE BOARD LOCK			
HARVEY	2004/11/05	(LEAD-FREE)			
APPROVED BY	DATE	MOLEX INCORPORATED			

MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	SD-67068-003	1 OF 4

DRAFT WHERE APPLICABLE
 MUST REMAIN WITHIN DIMENSIONS

SEE NOTES
 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

NOTES :

1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,
 (b) POLYESTER, GLASS FIBER FILLED, UL94V-0, COLOR: WHITE,
 TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

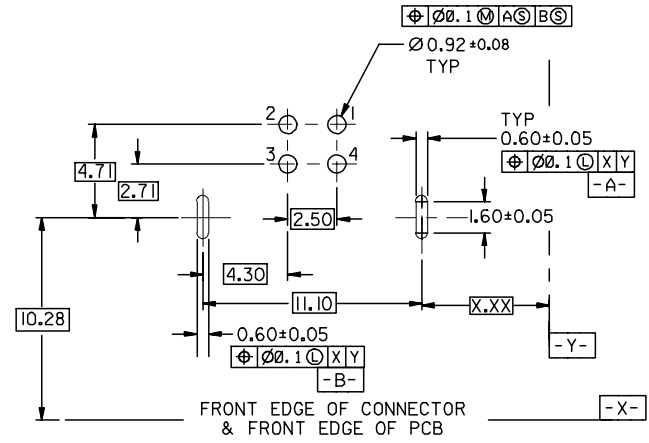
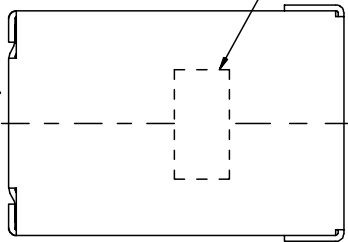
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

METAL SHELL :
 PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

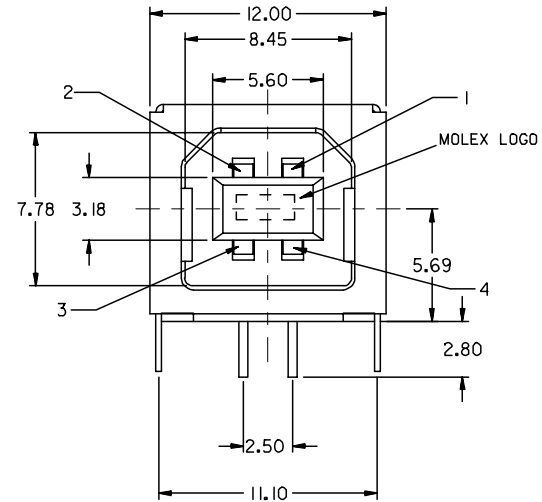
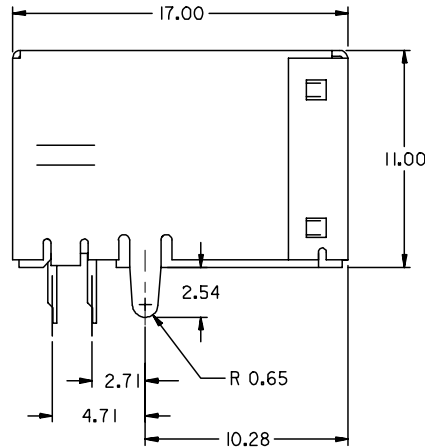
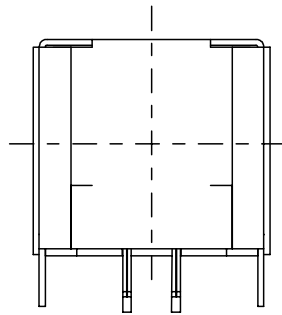
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05
 4 PRODUCT SPECIFICATION ; REFER TO PS-67998-0000

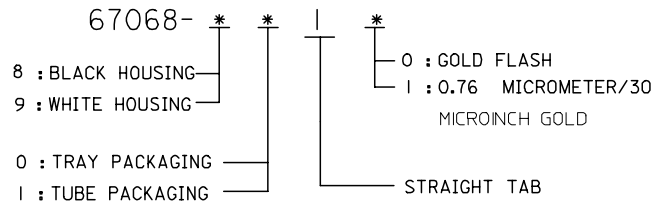
MOLEX ID OF MFG PLANT CODE



RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:



NEW RELEASE EC NO: SH2005-0142 DRWN: DAVID HU 2004/11/5 CHKD: HARVEY 2004/11/25 APPR: TYAP 2004/11/25	QUALITY SYMBOLS ▽=0 ∇=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 4:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
				DRAWN BY DAVID HU	DATE 2004/11/05	TITLE USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)		
				CHECKED BY	DATE 2004/11/05	APPROVED BY	DATE 2004/11/05	
				ANGULAR ± 3 °		MATERIAL NO.	DOCUMENT NO. SD-67068-003	SHEET NO. 2
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE NOTES		MOLEX INCORPORATED		
		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9 8 7 6 5 4 3 2 1

8 7 6 5 4 3 2 1

NOTES :
 1. MATERIAL :
 HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
 METAL SHELL : COPPER ALLOY

2. PLATING :
 TERMINAL :
 CONTACT AREA : (a) GOLD FLASH.
 (b) GLOD (Au), THICKNESS = 30 MICROINCH MINIMUM.
 /0.76 MICROMETER MINIMUM.

SOLDER TAIL :
 PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
 /1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

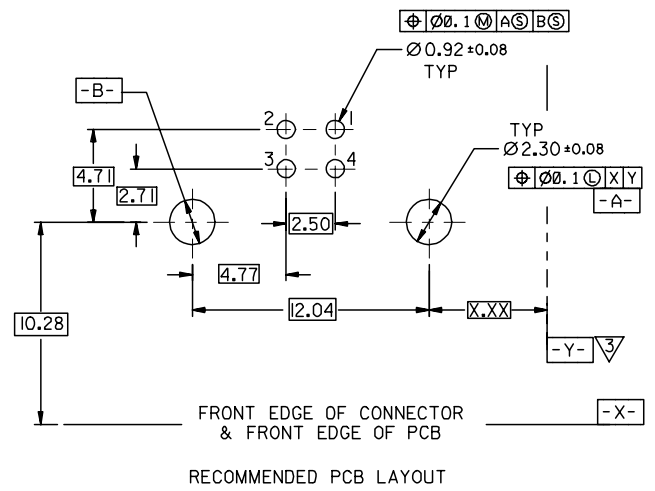
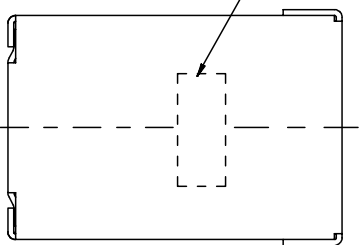
METAL SHELL :
 PURE TIN(SN), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
 /1.27 MICROMETER MINIMUM.

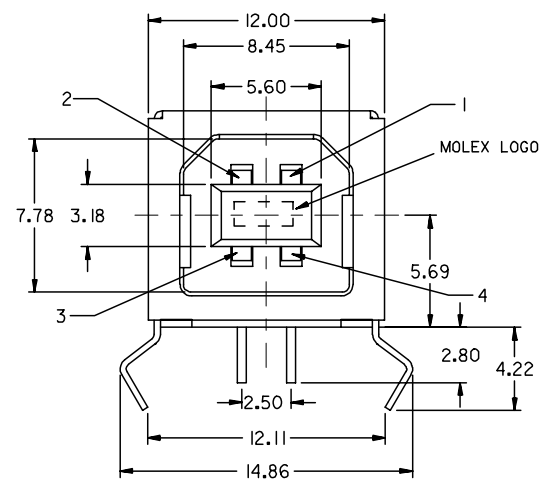
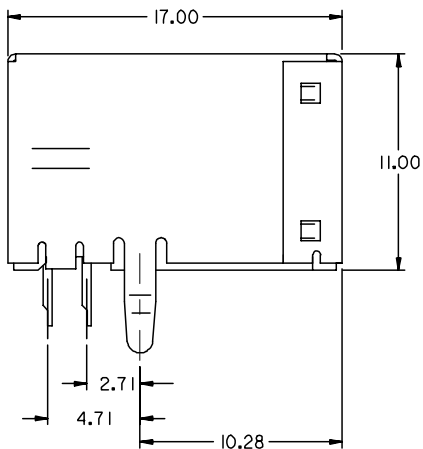
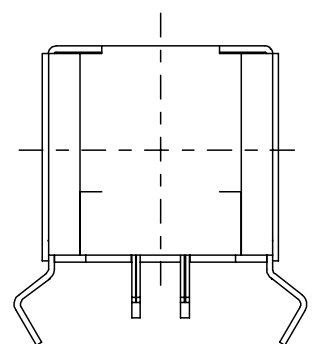
▽ DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



FRONT EDGE OF CONNECTOR
 & FRONT EDGE OF PCB
 RECOMMENDED PCB LAYOUT



PART NUMBER LEGEND:
 67068- 7041

ENG. NO

EDP NO.

SIMILAR ITEM

CAD FILE :

DO NOT SCALE DRAWING

				MATERIAL : SEE NOTES		MOLEX TAIWAN LTD. SHEET 3 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP.USB B TYPE CONNECTOR KINK TYPE BOARD LOCK (LEAD-FREE)						

ENG. NO SDA-67068-****

EDP NO.

SIMILAR ITEM

CAD FILE : S6706802

DO NOT SCALE DRAWING

NOTES :

1. MATERIAL :
HOUSING : (a) HIGH TEMP. NYLON, GLASS FIBER FILLED, UL94V-0, COLOR: BLACK,

TERMINAL : PHOSPHOR BRONZE
METAL SHELL : COPPER ALLOY

2. PLATING :

TERMINAL :
CONTACT AREA : (a) GOLD FLASH.
(b) GL0D (Au), THICKNESS = 30 MICROINCH MINIMUM.
/0.76 MICROMETER MINIMUM.

SOLDER TAIL :
PURE TIN(Sn) THICKNESS= 75 MICROINCH MINIMUM .
/1.9 MICROMETER MINIMUM.

UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

METAL SHELL :
PURE TIN(Sn) THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

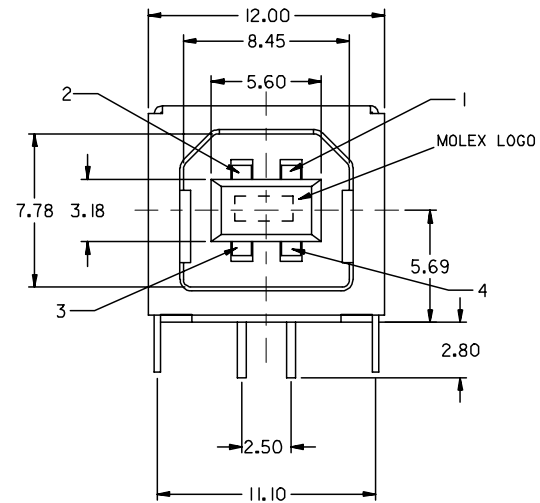
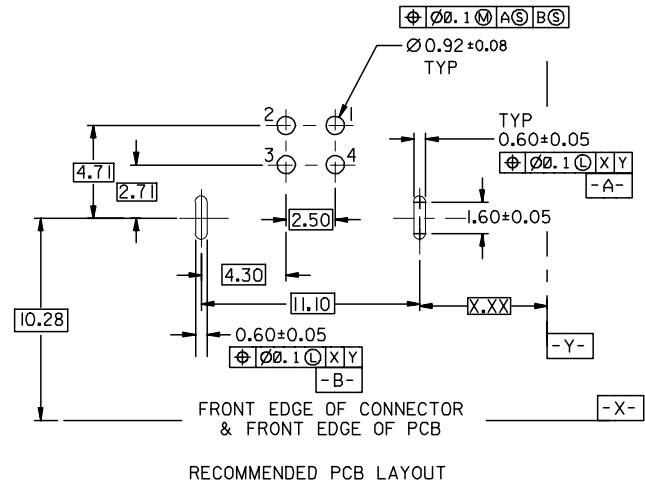
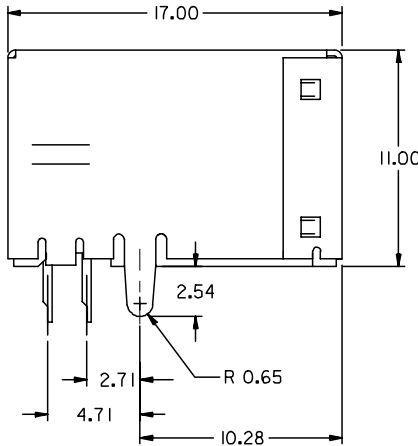
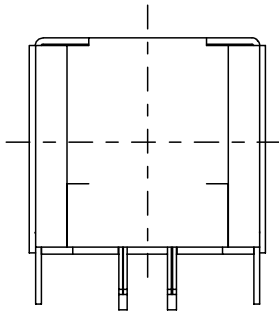
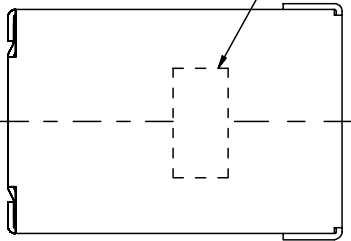
UNDER PLATE : NICKEL (Ni), THICKNESS= 50 MICROINCH MINIMUM.
/1.27 MICROMETER MINIMUM.

3 DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER

RECOMMENDED PCB THICKNESS : 1.60±0.05

4 PRODUCT SPECIFICATION : REFER TO PS-67998-0000

MOLEX ID OF MFG PLANT CODE



PART NUMBER LEGEND:

67068- 7051

				MATERIAL : SEE NOTES		 MOLEX TAIWAN LTD. SHEET 4 OF 4
				FINISH : SEE NOTES		
				WIRE RANGE :		GENERAL TOLERANCES ANGLE : ± 3° DIM : ± .25/.010
				INS. RANGE :		ENG. NO.: SD-67068-003
A	NEW RELEASE FOR LEAD-FREE		DAVID HU	2004/11/5		REV A
LTR	REVISION RECORD	ECN	DR	DATE	DRAWN BY 2004/11/5 DAVID HU	CHK'D BY
REVISE ONLY ON CAD SYSTEM					APPR'D BY	SCALE 4 : 1
TITLE : HIGH TEMP/USB B TYPE CONNECTOR WITH STRAIGHT TAB (LEAD-FREE)						